Ref#	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
Li	1	"6126768".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/04/01:15:19
L2	2	"5106441".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/04/01 15:22
1.3	278	349/190	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/04/01:15:32
L4	18	3 and silicon adj2 substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/04/01 15:32
L5	3125	"18" and spacer adj2 wall	US-PGPUB; USPAT; USOCR, EPO; JPO; DERWENT	OR	ON	2005/04/01:15:23
L6	0	4 and spacer adj2 wall	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/04/01 15:26
L7	14	4 and (spacer wall)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/04/01 15:26
L8	555	349/156	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/04/01 15:38
L9	63	8 and silicon adj2 substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/04/01:15:38
L10	51	9 and seal\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/04/01 15:34
L11	16	10 and (cut\$4 scrib\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/04/01 15:40
L12	6	11 and wall	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/04/01 15:36
L13	132	349/157	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/04/01 15:40

L14	5	13 and silicon adj2 substrate	US-PGPUB;	OR	ON	2005/04/01 15:40
			USPAT; USOCR; EPO; JPO;			
715	55A	349/158	DERWENT	O.D.	ON	::2005/04/01:15:40:
L15	334	349/136	US-PGPUB; USPAT;	OR	ON	2005/04/01 15:40
			USOCR; EPO; JPO; DERWENT			
L16	63	15 and silicon adj2 substrate	US-PGPUB;	OR	ON	2005/04/01 15:46
			USPAT; USOCR;			
			EPO; JPO; DERWENT			
L17	39	16 and (cut\$4 scrib\$3)	US-PGPUB, USPAT;	OR	ON	2005/04/01 15:58
			USOCR; EPO; JPO;			
L18	453721	"39" and seal\$3	DERWENT US-PGPUB;	OR	ON	2005/04/01 15:41
Lie	433721	37 and Seargs	USPAT; USOCR;	OR	ON	2003/04/01 13:41
			EPO; JPO; DERWENT			
L19	34	17 and seal\$3	US-PGPUB;	OR	ON	2005/04/01 15:41
			USPAT; USOCR;			
			EPO; JPO; DERWENT			
L20	19	19 and wall	US-PGPUB; USPAT;	OR	ON	2005/04/01 15:45
			USOCR; EPO; JPO;			
L21	196	349/189	DERWENT US-PGPUB;	OR	ON	2005/04/01 15:59
		2.77.13	USPAT; USOCR;	UK .	011	2003/04/01/13/35
			EPO; JPO; DERWENT			
L22	4	21 and silicon adj2 substrate	·US-PGPUB; USPAT;	OR	ON	2005/04/01 15:46
			USOCR; EPO; JPO;			
			DERWENT			
L23	24816	(cut\$4 scrib\$3) adj4 seal\$3	US-PGPUB; USPAT;	OR	ON	2005/04/01 15:58
			USOCR; EPO; JPO;			
L24	922	349/187	DERWENT US-PGPUB;	OR	ON	2005/04/01 15:59
			USPAT; USOCR;			
			EPO; JPO; DERWENT			
L25	41	24 and 23	US-PGPUB; USPAT;	OR	ON	2005/04/01 17:35
			USOCR; EPO; JPO;			
L26	82772	cilion adi2 wafer	DERWENT	OP	ON	2005/04/01 17-25
L20	02//2	silicon adj2 wafer	US-PGPUB; USPAT; USOCR;	OR	ON	2005/04/01 17:35
		·	EPO; JPO; DERWENT			
L27	21	24 and 26	US-PGPUB;	OR	ои	2005/04/01 17:42
			USPAT; USOCR;			
			EPO; JPO; DERWENT			

L28	4	21 and 26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/04/01 17:44
L29	6	3 and 26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/04/01:17:45
L30	20	8 and 26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/04/01 17:51
131	4	30 and wall	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/04/01 17:47
L32	26	15 and 26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/04/01 17:51